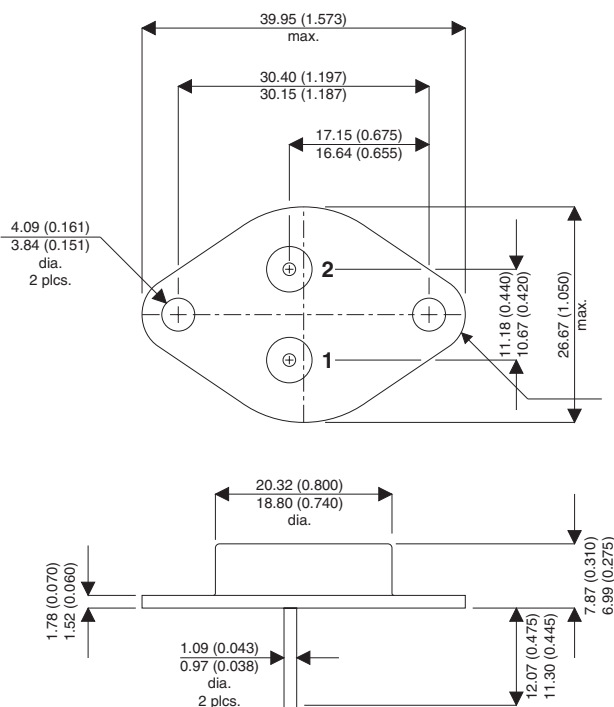


MECHANICAL DATA

Dimensions in mm (inches)



TO-3 (TO-204AA) Metal Package

Pin 1 – Source Pin 2 – Gate Case – Drain

**N-CHANNEL
POWER MOSFET**

V_{DSS} 400V
I_{D(cont)} 14A
R_{DS(on)} 0.300Ω

FEATURES

- REPETITIVE AVALANCHE RATINGS
- DYNAMIC DV/DT RATING
- HERMETICALLY SEALED
- SIMPLE DRIVE REQUIREMENTS
- EASE OF PARALLELING

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C unless otherwise stated)

| | | |
|-----------------------------------|--|---------------|
| V _{GS} | Gate – Source Voltage | ±20V |
| I _D | Continuous Drain Current (V _{GS} = 0, T _{case} = 25°C) | 14A |
| | (V _{GS} = 0, T _{case} = 100°C) | 9.0A |
| I _{DM} | Pulsed Drain Current ¹ | 56A |
| P _D | Power Dissipation @ T _{case} = 25°C | 150W |
| | Linear Derating Factor | 1.2W/°C |
| E _{AS} | Single Pulse Avalanche Energy ³ | 11.3mJ |
| I _{AR} | Avalanche Current ¹ | 14A |
| E _{AR} | Repetitive Avalanche Energy ¹ | 15mJ |
| dv/dt | Peak Diode Recovery ⁴ | 4.0V/ns |
| T _J , T _{stg} | Operating and Storage Temperature Range | -55 to +150°C |

Notes

- 1) Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
- 2) Repetitive Rating – Pulse width limited by maximum junction temperature.
- 3) V_{DD} = 50V, Peak I_L = 14A, Starting T_J = 25°C
- 4) I_{SD} ≤ 14A, di/dt ≤ 145A/μs, V_{DD} ≤ 400V, T_J ≤ 150°C, Suggested R_G = 2.35Ω

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ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

| Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|--|---|----------------------|------------|----------------------|
| STATIC ELECTRICAL RATINGS | | | | | |
| BV_{DSS} | Drain – Source Breakdown Voltage | $V_{GS} = 0V$ | $I_D = 1mA$ | 400 | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Temperature Coefficient of Breakdown Voltage | Reference to $25^{\circ}C$ $I_D = 1mA$ | | 0.46 | $V/^{\circ}C$ |
| $R_{DS(on)}$ | Static Drain – Source On-State Resistance | $V_{GS} = 10V$ | $I_D = 9.0A$ | | 0.300 |
| | | $V_{GS} = 10V$ | $I_D = 14A$ | | 0.400 |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}$ | $I_D = 250\mu A$ | 2.0 | 4.0 |
| g_{fs} | Forward Transconductance | $V_{DS} \geq 15V$ | $I_{DS} = 9.0A$ | 6.0 | S ($\bar{\omega}$) |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{GS} = 0V$ | $V_{DS} = 320V$ | | 25 |
| | | | $T_J = 125^{\circ}C$ | | 250 |
| I_{GSS} | Gate – Source Leakage Forward | $V_{GS} = +20V$ | | | +100 |
| I_{GSS} | Gate – Source Leakage Reverse | $V_{GS} = -20V$ | | | -100 |
| DYNAMIC CHARACTERISTICS | | | | | |
| C_{iss} | Input Capacitance | $V_{GS} = 0V$ | | 2660 | pF |
| C_{oss} | Output Capacitance | $V_{DS} = 25V$ | | 680 | |
| C_{rss} | Reverse Transfer Capacitance | $f = 1MHz$ | | 250 | |
| Q_g | Total Gate Charge | $V_{GS} = 10V$ | | 52 | 110 |
| Q_{gs} | Gate – Source Charge | $I_D = 14A$ | | 5.0 | 18 |
| Q_{gd} | Gate – Drain (“Miller”) Charge | $V_{DS} = 200V$ | | 25 | 65 |
| $t_{d(on)}$ | Turn–On Delay Time | $V_{DD} = 200V$ | | | 35 |
| t_r | Rise Time | $I_D = 14A$ | | | 190 |
| $t_{d(off)}$ | Turn–Off Delay Time | $R_G = 2.35\Omega$ | | | 170 |
| t_f | Fall Time | | | | 130 |
| SOURCE – DRAIN DIODE CHARACTERISTICS | | | | | |
| I_S | Continuous Source Current | | | | 14 |
| I_{SM} | Pulse Source Current ² | | | | 56 |
| V_{SD} | Diode Forward Voltage ¹ | $I_S = 28A$ | $T_J = 25^{\circ}C$ | | 1.7 |
| | | $V_{GS} = 0$ | | | |
| t_{rr} | Reverse Recovery Time | $I_F = 28A$ | $T_J = 25^{\circ}C$ | | 1200 |
| Q_{rr} | Reverse Recovery Charge ¹ | $d_i / d_t \leq 100A/\mu s$ | $V_{DD} \leq 50V$ | | 250 |
| t_{on} | Forward Turn–On Time | | | Negligible | |
| PACKAGE CHARACTERISTICS | | | | | |
| $L_D + L_S$ | Total Inductance (measured from the centre of drain pad to center of source pad) | | | 6.1 | nH |
| THERMAL CHARACTERISTICS | | | | | |
| R_{thJC} | Thermal Resistance Junction – Case | | | 0.83 | $^{\circ}C/W$ |
| R_{thJA} | Thermal Resistance Junction – Ambient (Typical socket mount) | | | 30 | |

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